



General Description

These N-Channel enhancement mode power field effect transistors are using SGT MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

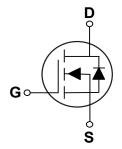
BV _{DSS}	R _{DS(ON)}	Ι _D
120 V	7.5 mΩ	90 A

Features

- $R_{DS(ON)} \le \overline{7.5m\Omega} \overline{@V_{GS}} = 10V$
- Fast Switching
- · Improved dv/dt Capability
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- Power Management Switches
- · DC/DC Converter

Absolute Maximum Ratings T _A =25°C unless otherwise noted						
Symbol	Parameter	Value	Units			
V_{DS}	Drain-Source Voltage	120	V			
V_{GS}	Gate-Source Voltage	±20	V			
I _D	Drain Current - Continuous (T _C =25°C)	90	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	360	Α			
EAS	Single Pulse Avalanche Energy (NOTE 2)	259.2	mJ			
P_{D}	Power Dissipation (T _C =25°C)	104	W			
T_J	Operating Junction Temperature Range	-55 to 150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		NN7P5				

Thermal Characteristics					
Symbol	Parameter	Value	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	56	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	1.2	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	120			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =120V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V		-	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			7.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	2		4	V
gfs	Forward Transconductance	V _{DS} =10V , I _D =20A		70		S

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			43		
Q_{gs}	Gate-Source Charge	V_{DS} =60V , V_{GS} =10V , I_{D} =20A		13.8		nC
Q_gd	Gate-Drain Charge			8		
$T_{d(on)}$	Turn-On Delay Time			14.3		
T _r	Rise Time	V_{DD} =60V , V_{GS} =10V , R_{G} =3 Ω ,		12		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =20A		33.5		113
T_f	Fall Time			8.6		
C_{iss}	Input Capacitance			3370		
C _{oss}	Output Capacitance	V_{DS} =60V , V_{GS} =0V , F=1MHz		471		pF
C_{rss}	Reverse Transfer Capacitance			11		
R_g	Gate resistance	V _{GS} =0V , V _{DS} =0V , f=1MHz		2.6		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			90	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =20A			1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A , dI/dt=500A/us		46		nS
Q_{rr}	Body Diode Reverse Recovery Charge			278		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The EAS data shows Max. rating. The test condition is V_{DD} =50V, V_{GS} =10V, L=0.4mH, I_{AS} =36A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. This value is guaranteed by design hence it is not included in the production test.





Characteristics Curves

FIG. 1-Transfer Characteristics

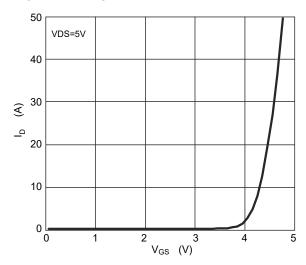


FIG. 2-I_S vs V_{SD}

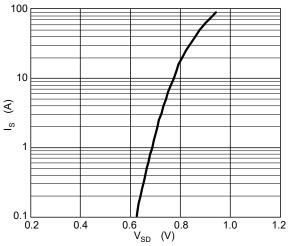


FIG. 3-R $_{\rm DS(on)}$ vs I $_{\rm D}$

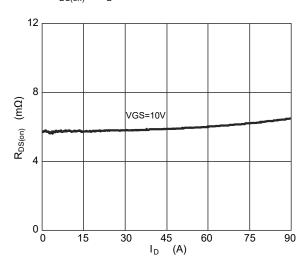


FIG. 4-Normalized $R_{DS(ON)}$ vs T_J

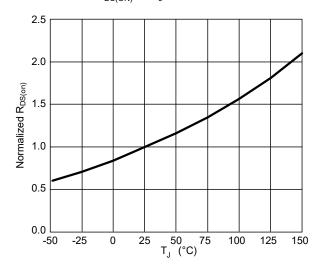


FIG. 5-Gate Charge Characteristics

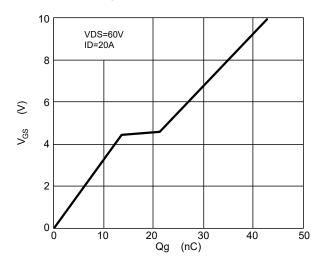
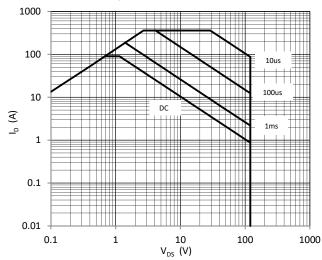


FIG. 6-Safe Operating Area

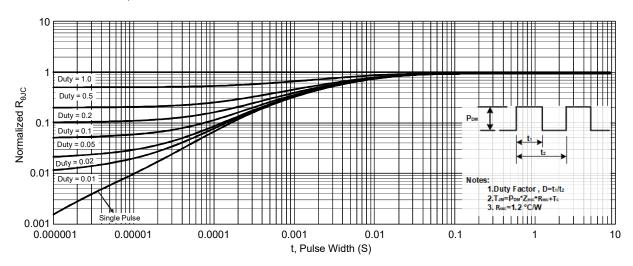




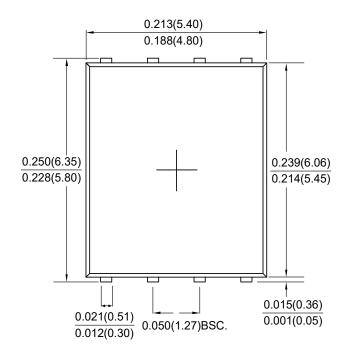


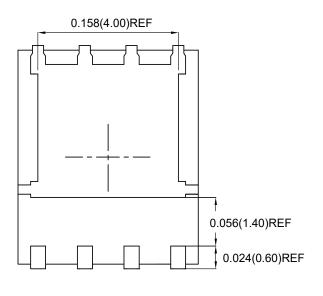
Characteristics Curves

FIG. 7-Transient Thermal Impedance



Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





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